

**ON Semiconductor®** 

# FDS4675-F085 40V P-Channel PowerTrench<sup>®</sup> MOSFET

## **General Description**

This P-Channel MOSFET is a rugged gate version of ON Semiconductor's advanced Power Tranch process. It has been optimized for power management applications requiring a wide range of gave drive voltage ratings (4.5 V - 20 V).

# **Applications**

- **Powermanagement**
- . Load switch
- **Battery protection**



## Features

-11 A, -40 V  $\ R_{DS(ON)}$  = 0.013  $\Omega$  @  $V_{GS}$  = -10 V  $R_{DS(ON)} = 0.017 \Omega @ V_{GS} = -4.5 V$ 

- Fast switching speed
- High performance trench technology for extremely low R<sub>DS(ON)</sub>

4

3

2

1

- High power and current handling capability
- Qualified to AEC Q101

5

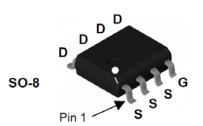
6

7

8

12mm

**RoHS** Compliant



## Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

FDS4675-F085

Symbol		Parame	ter	Ratings		Units	
V <sub>DSS</sub>	Drain-Sourc	e Voltage		-40	-40		
V <sub>GSS</sub>	Gate-Source	e Voltage		-	±20		
I <sub>D</sub>	Drain Current		Continuous	-11 <sup>(Note 1a)</sup>		Α	
			Pulsed	-50		А	
P <sub>D</sub>	Power Dissipation for Single Operation			2.4 (steady st	2.4 (steady state) (Note 1a)		
				1.4 <sup>(Not</sup>	1.4 <sup>(Note 1b)</sup>		
				1.2 <sup>(Not</sup>	1.2 <sup>(Note 1c)</sup>		
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range			-55 to +	-55 to +150		
Thermal	Characte	ristics					
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient			62.5 (steady state), \$	62.5 (steady state), 50 (10 sec) <sup>(Note 1a)</sup>		
$R_{ heta JA}$	Thermal Re	sistance, Junction to Am	125 <sup>(Not</sup>	125 <sup>(Note 1c)</sup>			
$R_{ ext{ heta}JC}$	Thermal Re	sistance, Junction to Ca	25 <sup>(Not</sup>	25 <sup>(Note 1)</sup>			
ackage	Marking	and Ordering In	nformation	L			
Device Marking		Device	Reel Size	Tape width Quant		/	

13"

FDS4675

2500 units



FDS4675-F085
— 40V
P-ChannelTrench <sup>®</sup>
MOSFET

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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
ff Characterist	lics					
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_D = -250 \mu A$	-40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 µA, Referenced to 25°C		-34		mV/
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -32 V_{,} V_{GS} = 0 V$			-1	μA
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	$V_{GS} = 20 V, V_{DS} = 0 V$			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	$V_{GS} = -20 V, V_{DS} = 0 V$			-100	n/
n Characterist	tics (Note 2)					<u> </u>
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-1.4	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$ , Referenced to $25^{\circ}C$		4.6		mV,
		$V_{GS}$ = -10 V, $I_{D}$ = -11 A		10	13	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS}$ = -4.5 V, I <sub>D</sub> = -9.5 A		13	17	m
		$V_{GS}$ = -10 V, $I_D$ = -11 A, $T_J$ = 125 °C		15	21	1
<b>g</b> <sub>FS</sub>	Forward Transconductance	$V_{DS} = -5 V, I_{D} = -11 A$		44		S
ynamic Charac	cteristics					
CISS	Input Capacitance			4350		pl
C <sub>oss</sub>	Output Capacitance	$V_{\text{DS}} = -20 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1 \text{ MHz}$		622		р
$C_{RSS}$	Reverse Transfer Capacitance			290		р
witching Chara	acteristics <sup>(Note 2)</sup>	•				
t <sub>d(on)</sub>	Tum-On Delay Time			40	64	n
tr	Turn-On Rise Time	$V_{DD} = -20 V, I_D = -1 A$		49	79	n
$t_{d(off)}$	Tum-Off Delay Time	$V_{GS}$ = -4.5 V, $R_{GEN}$ = 6 $\Omega$		100	160	n
t <sub>f</sub>	Turn-Off Fall Time			60	96	n
Qg	Total Gate Charge			40	56	n
$Q_{gs}$	Gate-Source Charge	$V_{\text{DS}}$ = -20 V, $I_{\text{D}}$ = -11 A, $V_{\text{GS}}$ = -4.5 V		11		n
$Q_{gd}$	Gate-Drain Charge			13		n
rain-Source Di	ode Characteristics and Maximum Ra	tings				
ls	Maximum Continuous Drain-Source Diode Forward Current				-2.1	A
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ A}, \text{ I}_{S} = -2.1 \text{ A}^{(Note \ 2)}$		-0.7	-1.2	١

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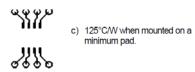
R<sub>0.1A</sub> is the sum of the junction to case and case to ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0.1C</sub> is guaranteed by design while R<sub>0.CA</sub> is determined by the user's board design.



a) 50°C/W when mounted on a 1in2 pad of 2 oz copper

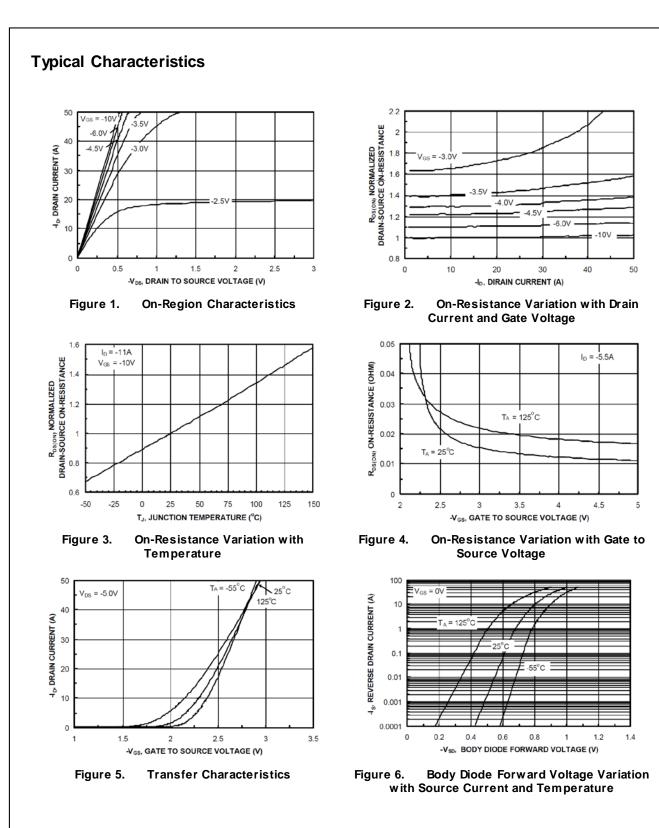


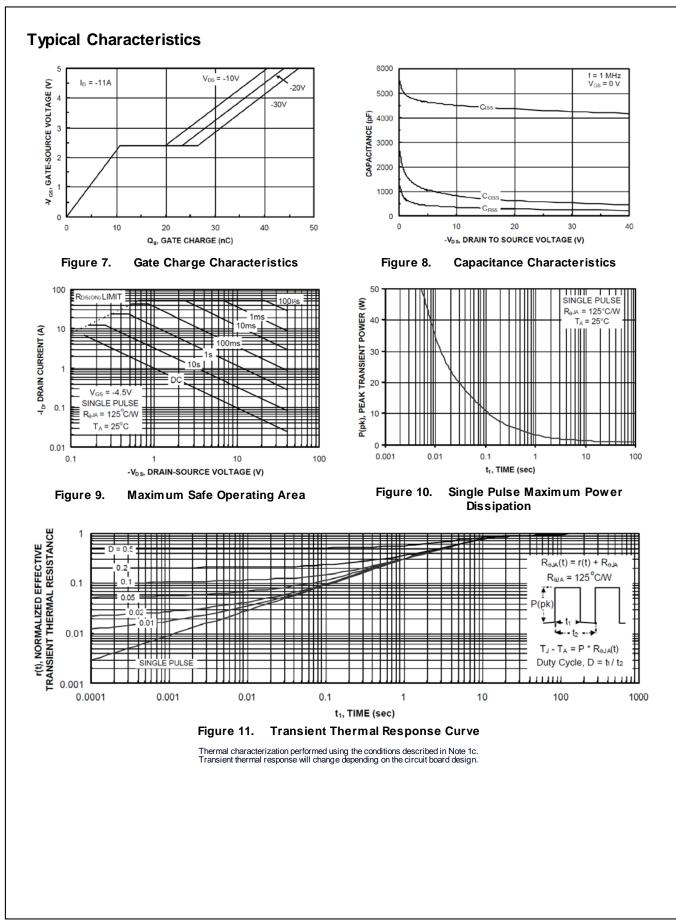
b) 105°C/W when mounted on a .04 in<sup>2</sup> pad of 2 oz copper

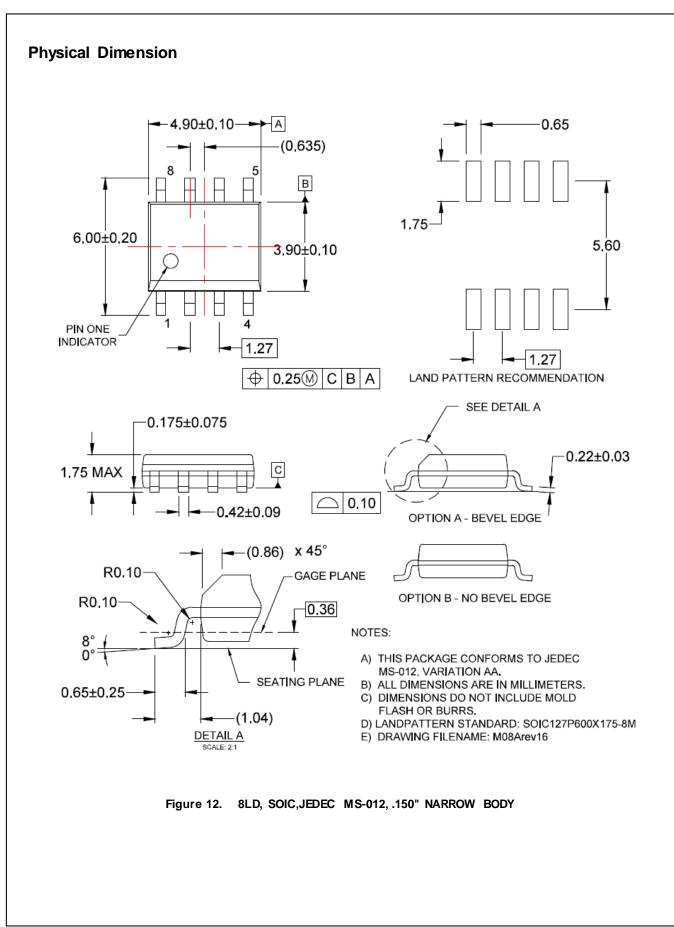


Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty Cycle < 2.0%







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